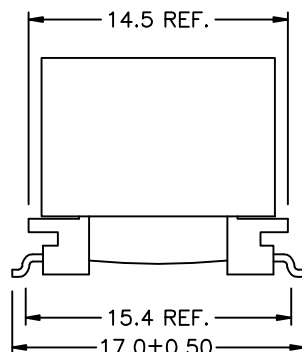
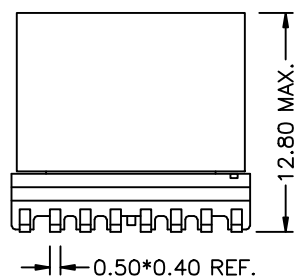
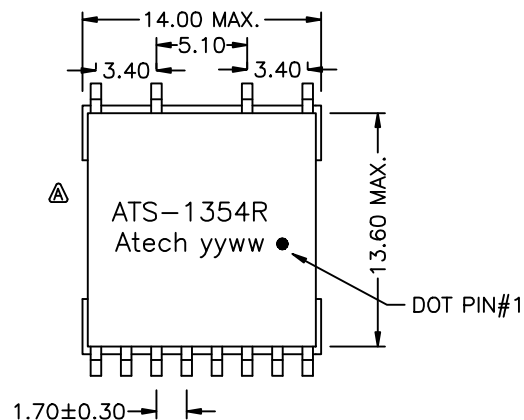
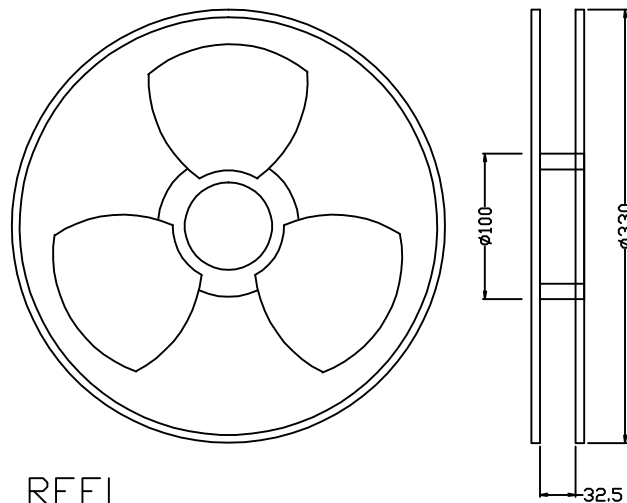
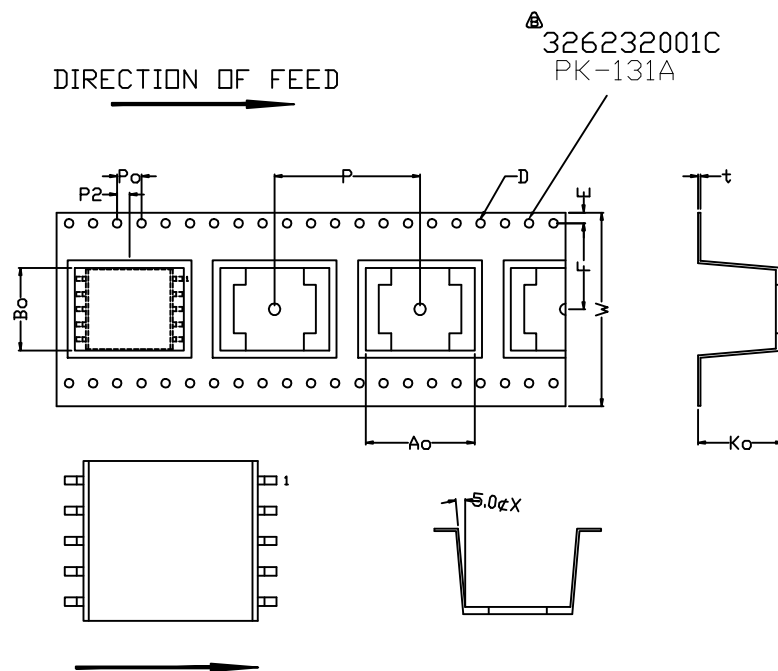


ELECTRICAL CHARACTERISTICS :

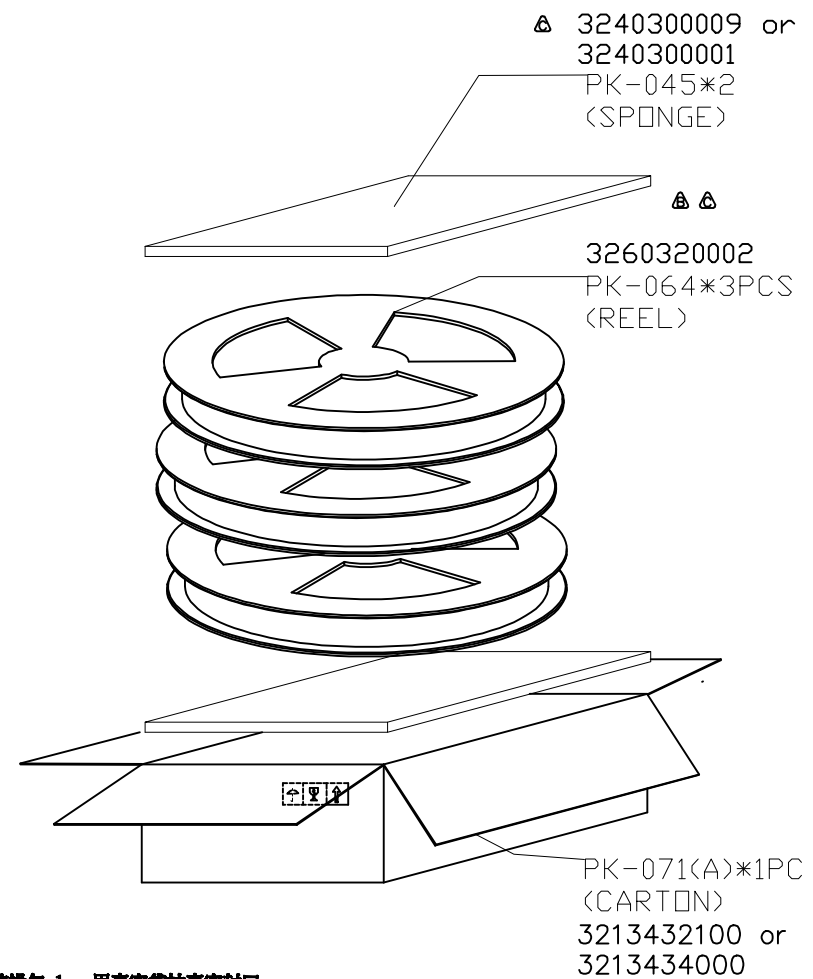
- DCR : PIN 1-4 (PIN 2-3 SHORT) = 0.36Ω MAX.
PIN 5-8 (PIN 6-7 SHORT) = 0.47Ω MAX.
PIN 16-9 (PIN 11-14 SHORT) = 1.25Ω MAX.
- INDUCTANCE (@10KHz, 0.1Vrms) :
PIN 16-9 (11-14 SHORT) = 400uH ±10%
- LEAKAGE INDUCTANCE (@100KHz, 0.1Vrms) :
PIN 16-9 (11-14, 1-2-3-4, 5-6-7-8 SHORT) = 4.5uH MAX.
- T.H.D. (@30KHz, 3.162Vrms) :
PIN 16-9 TO PIN1-4 (2-3, 6-7, 11-14 SHORT) = -82dB MAX.
PIN 16-9 W/H 100Ω, PIN 1-4 W/H 13Ω, PIN 5-8 W/H 13Ω
- TURN RATIO (@10KHz, 0.1Vrms) :
PIN 16-9 (11-14 SHORT) : 1-4 (2-3 SHORT) = 2.7 ±5%
PIN 16-9 (11-14 SHORT) : 5-8 (6-7 SHORT) = 2.7 ±5%
- HI-POT : (@1.5KVAC, 500uA, 2S) PRI-SEC
- RoHS COMPLIANTE

								TITLE xDSL TRANSFORMER	
B	ADD PHOTO	09/06/2019	SHIRLEY	TINA	TINA			DWG. NO. ATS-1354R	
A	CHANGE PRINT & T.H.D	05/09/2019	SHIRLEY	DICK	DICK				
	RELEASE	02/13/2014	SHIRLEY	BETTY	BETTY	UNITS: M/M		SAFETY	
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 02/13/2014		P/N:	
REVISIONS								SHEET 1 of 2	
								DRAW SHIRLEY	



REEL

ONE REEL 200 PCS
ONE CARTON 3 REEL (600 PCS)



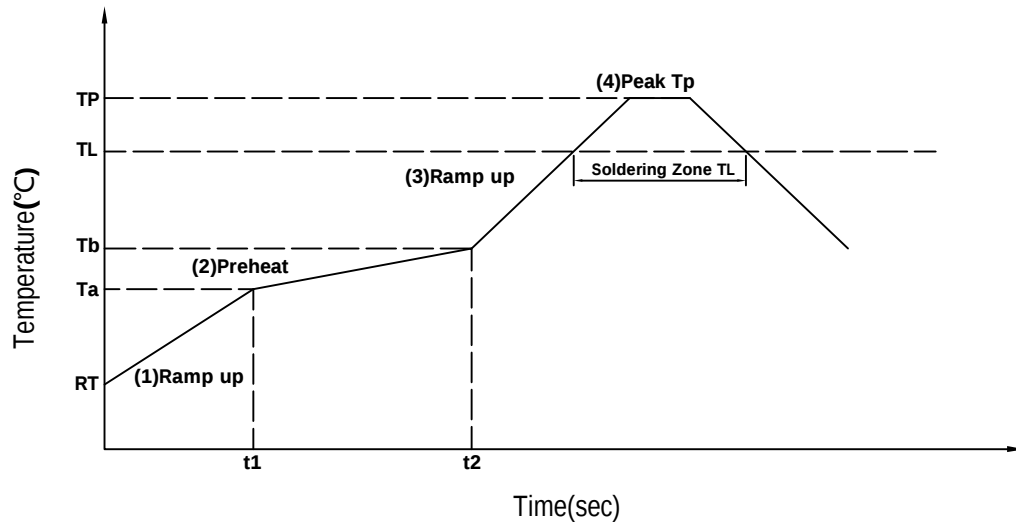
每箱放乾燥包 1pc 用真空袋抽真空封口
2780000000 3255048421 or 3255048420

ITEM	W	Ao	Bo	Ko	P	F	E	D	DI	Po	P2	t
DIM	32.00 ^{+0.30} _{-0.30}	18.00 ^{+0.10} _{-0.10}	13.60 ^{+0.10} _{-0.10}	14.10 ^{+0.10} _{-0.10}	24.00 ^{+0.10} _{-0.10}	14.20 ^{+0.10} _{-0.10}	1.75 ^{+0.10} _{-0.10}	1.50 ^{+0.10} _{-0.00}	2.00 ^{+0.25} _{-0.00}	4.00 ^{+0.10} _{-0.10}	2.00 ^{+0.10} _{-0.10}	0.40 ^{+0.05} _{-0.05}

C	CHANGE PART NO.	03/06/2012	SHIRLEY	JOAN	JOAN		TITLE		PACKING	
B	CHANGE PART NO.	03/11/2011	SHIRLEY	DICK	DICK		DWG. NO.		968TS71800	
A	ADD SPONG&CARTON	10/04/2005	BART	PAIR	SUEDY		UNITS:		SAFETY	
	RELEASE	04/13/2006	PAIR	AL	EUGENE		M/M			
ND	DESCRIPTION	DATE	BY	CHK	APPD		DATE		SHEET 1 OF 1	
REVISIONS							04/13/06		DRAW	
									Pair	



Pb-free Soldering IR Reflow(SMD)



- 1,MSL Grade: 1 Level 2,Floor life: 2years 3,Condition:≤30°C RH 85%
2,Form-1(Reference JEDEC J-STD-020D Table 5-2)

IR reflow profile		Pb-free
step#	Profile Feature	Condition/Duration
step1	Ramp-up rate	3°C/second max
step2	Preheat:150°C-200°C(Ta-Tb)	t1-t2:60-120seconds
step3	Ramp-up rate(TL to Tp)	3°C/second max
	Temperature maintained above 217°C	60-150seconds
step4	Peak temperature(Tp)	260+0/-5°C
	Time within 5°C of actual peak temperature	30seconds max
Ramp-down rate(Tp to TL)		6°C/second max

- 3,Form-2(Reference JEDEC J-STD-020D Table 4-2)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6mm	260+0/-5°C	260+0/-5°C	260+0/-5°C
1.6mm-2.5mm	260+0/-5°C	250+0/-5°C	245+0/-5°C
>2.5mm	250+0/-5°C	245+0/-5°C	245+0/-5°C